



## Description

### JMT Dual N Enhancement Mode Power MOSFET

#### Features

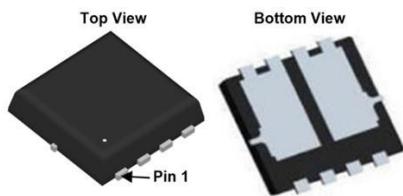
- 30V,12A
- $R_{DS(ON)} < 20m\Omega$  @  $V_{GS} = 10V$
- $R_{DS(ON)} < 29m\Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

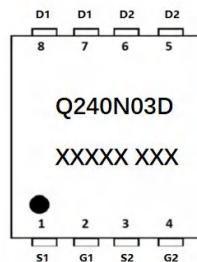
- Battery Protection
- Load Switch
- Power Management



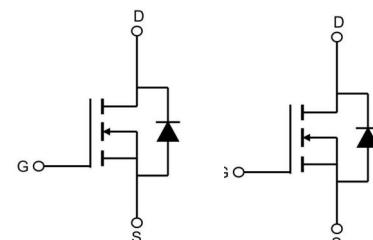
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



PDFN3x3-8L-D



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
Q240N03D	JMTQ240N03D	TAPING	PDFN3x3-8L-D	13inch	5000	50000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	12	A
		$T_C = 100^\circ C$	7.8	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		48	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		9.9	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ C$	4.8	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		26	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

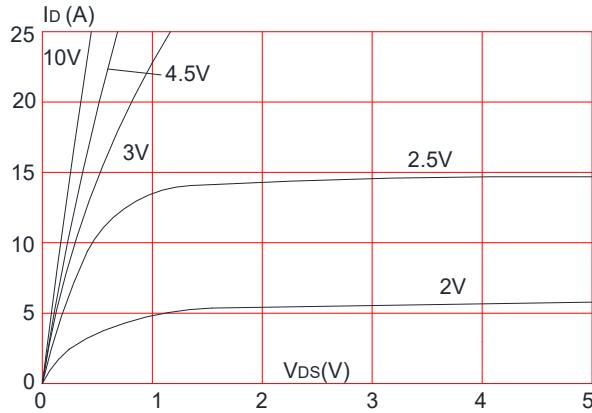
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=5\text{A}$	-	15	20	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	-	21	29	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	490	-	pF
$C_{oss}$	Output Capacitance		-	79	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	61	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}$ , $I_D=5.8\text{A}$ , $V_{GS}=10\text{V}$	-	5.2	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.9	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.3	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}$ , $I_D=3\text{A}$ , $V_{GS}=10\text{V}$ , $R_{REN}=3\Omega$	-	4.5	-	ns
$t_r$	Turn-on Rise Time		-	2.5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	14.5	-	ns
$t_f$	Turn-off Fall Time		-	3.5	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	12	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	48	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=12\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

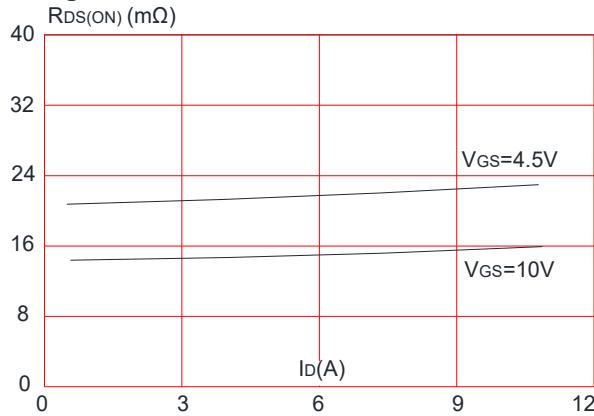
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=15\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=6.3\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

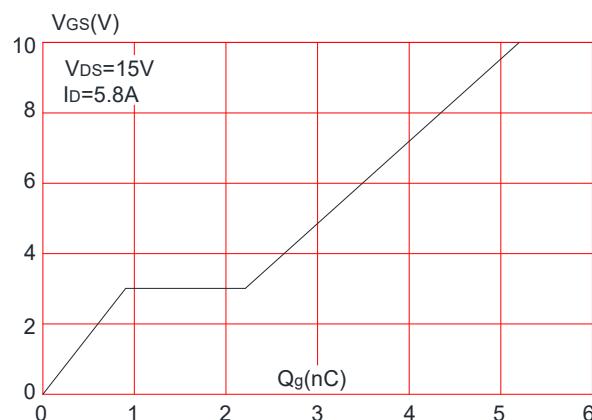
**Figure 1:** Output Characteristics



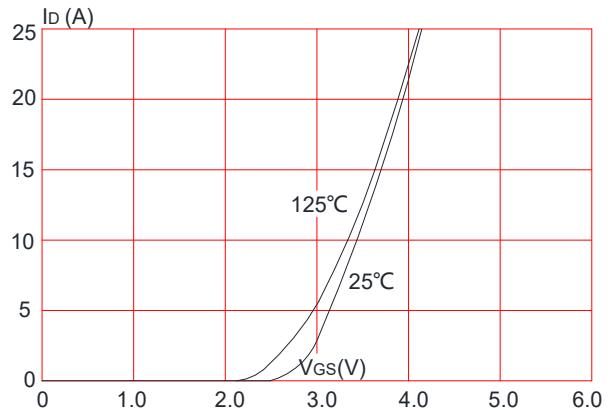
**Figure 3:** On-resistance vs. Drain Current



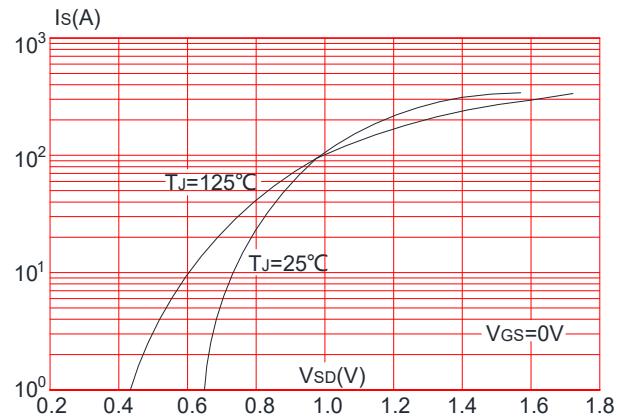
**Figure 5:** Gate Charge Characteristics



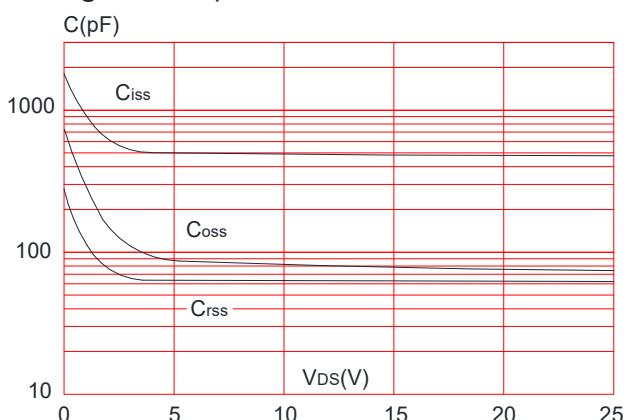
**Figure 2:** Typical Transfer Characteristics



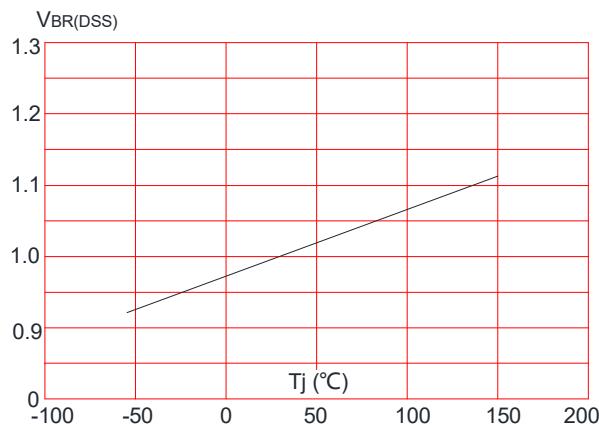
**Figure 4:** Body Diode Characteristics



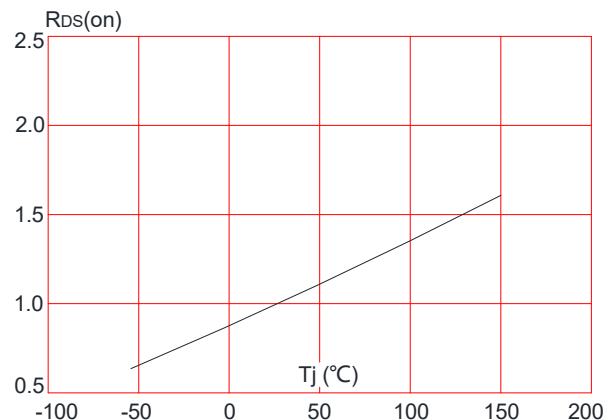
**Figure 6:** Capacitance Characteristics



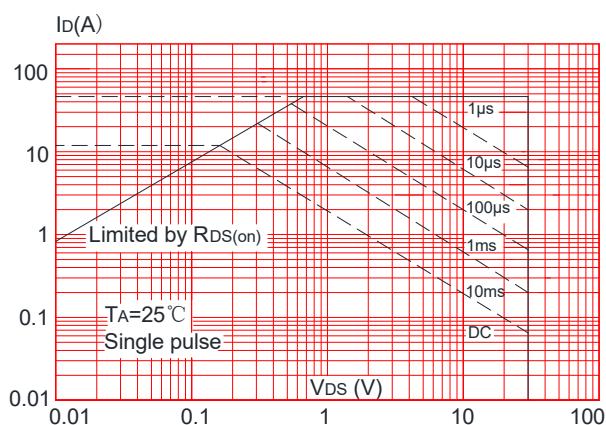
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



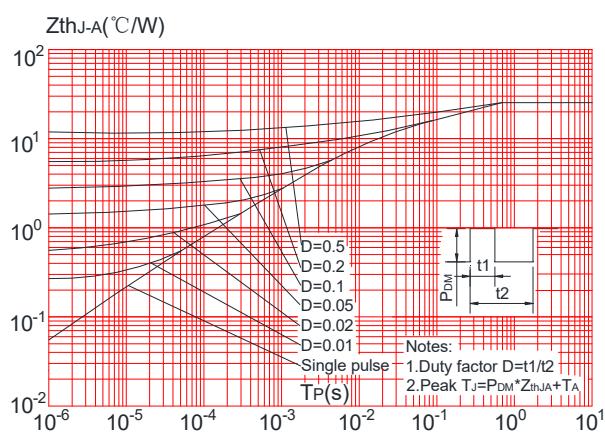
**Figure 8:** Normalized on Resistance vs. Junction Temperature



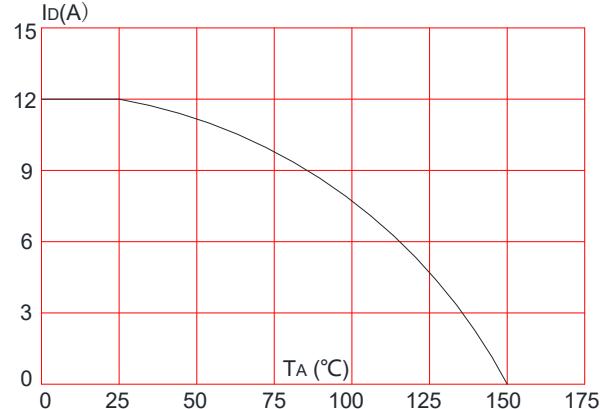
**Figure 9:** Maximum Safe Operating Area



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



## Test Circuit

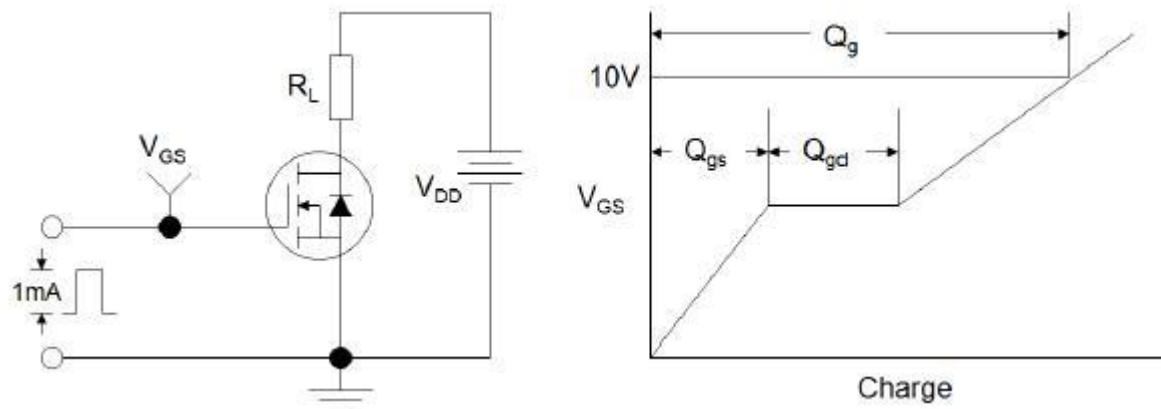


Figure1:Gate Charge Test Circuit & Waveform

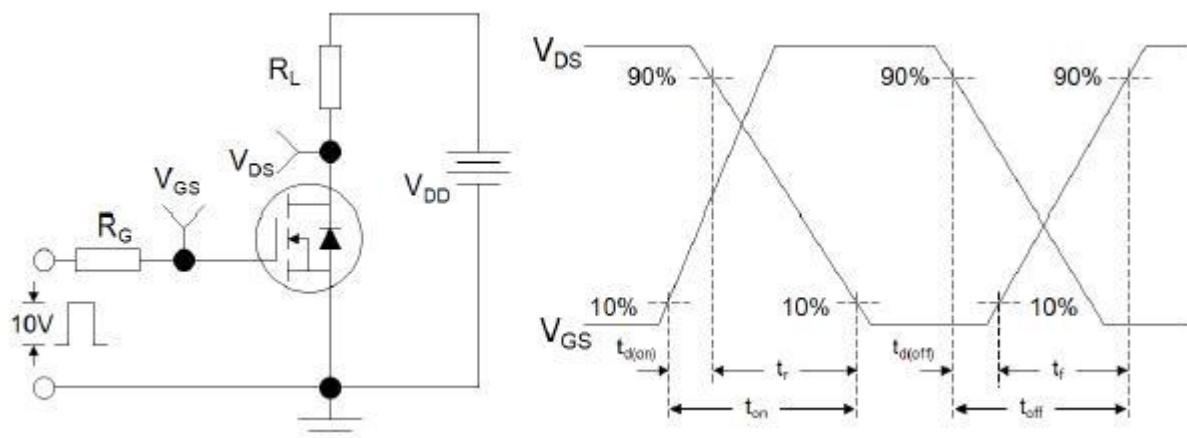


Figure 2: Resistive Switching Test Circuit & Waveforms

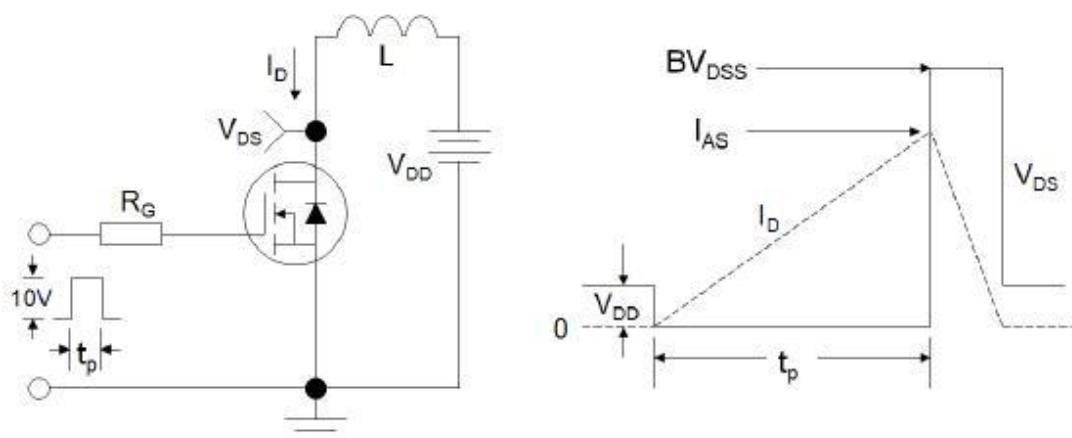
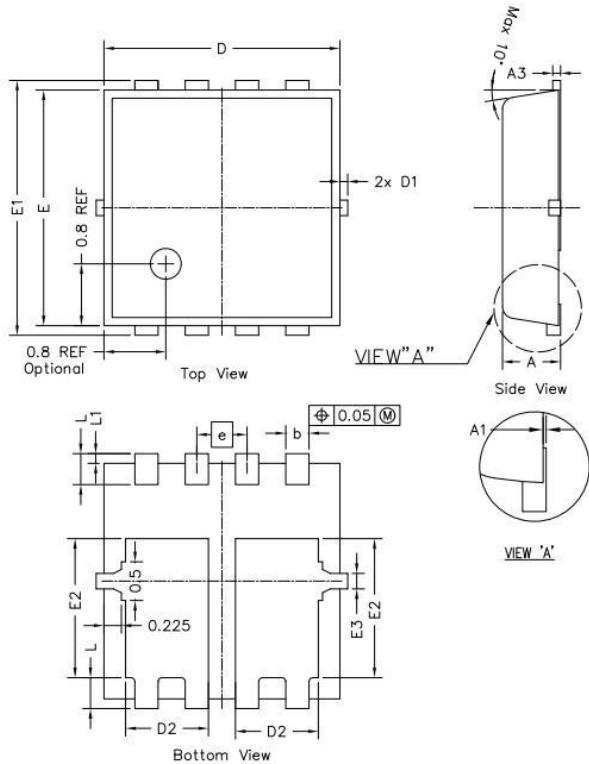


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data-PDFN3x3-8L-D



SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.750	0.800	0.028	0.030	0.031
A1	---	---	0.050	----	----	0.002
A3	0.144	0.152	0.202	0.006	0.006	0.008
b	0.250	0.300	0.350	0.010	0.012	0.014
e	0.65 BSC			0.026 BSC		
D	2.950	3.050	3.150	0.116	0.120	0.124
E	2.950	3.050	3.150	0.116	0.120	0.124
D1	---	---	0.125	----	----	0.005
E1	3.200	3.300	3.400	0.126	0.130	0.134
D2	0.970	1.070	1.170	0.038	0.042	0.046
E2	1.700	1.800	1.900	0.067	0.071	0.075
E3	0.150	0.200	0.250	0.006	0.008	0.010
L	0.300	0.400	0.500	0.012	0.016	0.020
L1	0.075	0.125	0.175	0.003	0.005	0.007

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